

DDR3 Code Information

Component

Part Number Decoder

SAMSUNG ELECTRONICS RESERVES THE RIGHT TO CHANGE PRODUCTS, INFORMATION AND SPECIFICATIONS WITHOUT NOTICE.

Products and specifications discussed herein are for reference purposes only. All information discussed herein is provided on an "AS IS" basis, without warranties of any kind.

This document and all information discussed herein remain the sole and exclusive property of Samsung Electronics. No license of any patent, copyright, mask work, trademark or any other intellectual property right is granted by one party to the other party under this document, by implication, estoppel or otherwise.

Samsung products are not intended for use in life support, critical care, medical, safety equipment, or similar applications where product failure could result in loss of life or personal or physical harm, or any military or defense application, or any governmental procurement to which special terms or provisions may apply.

For updates or additional information about Samsung products, contact your nearest Samsung office.

All brand names, trademarks and registered trademarks belong to their respective owners.

© 2009 Samsung Electronics Co., Ltd. All rights reserved.

Part Number Decoder

K **4** **B** X X X X X X X - X X X X X X

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

1. Memory (K)

2. DRAM : 4

3. Small Classification

B : DDR3 SDRAM

4~5. Density

51 : 512Mb

1G : 1G

2G : 2G

4G : 4G

6~7. Bit Organization

04 : x4

08 : x8

16 : x16

8. # of Internal Banks

3 : 4 Banks

4 : 8 Banks

5 : 16 Banks

9. Interface, VDD, VDDQ

6 : SSTL, 1.5V, 1.5V

10. Generation

M : M-die

A : A-die

B : B-die

C : C-die

D : D-die

E : E-die

F : F-die

G : G-die

H : H-die

11. "-"

12. Package

Z : FBGA (Lead-Free)

H : FBGA (Lead-Free & Halogen-Free)

J : FBGA (Lead-Free, DDP)

M : FBGA (Lead-Free & Halogen-Free, DDP)

B : FBGA (Lead-Free & Halogen-Free, Flip Chip)

13. Temp, Power

C : Commercial Temp.(0°C ~ 85°C), Normal Power

Y : Commercial Temp.(0°C ~ 85°C), Low VDD(1.35V)

14~15. Speed (Wafer/Chip Biz/BGD: 00)

F7 : DDR3-800 (400Mhz@CL=6, tRCD=6, tRP=6)

F8 : DDR3-1066 (533MHz@CL=7, tRCD=7, tRP=7)

H9 : DDR3-1333 (667MHz@CL=9, tRCD=9, tRP=9)

K0 : DDR3-1600 (800MHz@CL=11, tRCD=11, tRP=11)

MA : DDR3-1866 (933MHz@CL=13, tRCD=13, tRP=13)

K 4 B X X X X X X X - X X X X X X X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

16. Packing "Packing Type Reference"

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
Component	TAPE & REEL	T
	Other (Tray, Tube, Jar)	0 (Number)
	Stack	S
Module	MODULE TAPE & REEL	P
	MODULE Other Packing	M

17~18. Customer "Customer List Reference"